



## Product Change Notification / LIAL-07RPOQ740

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### Date:

11-Aug-2022

### Product Category:

Ethernet PHYs

### PCN Type:

Manufacturing Change

### Notification Subject:

CCB 5135 Initial Notice: Qualification of a new lead frame with more Ag area on DAP surface prep for selected KSZ8081 and KSZ8091 device families available in 32L VQFN (5x5x0.9mm) package assembled at MTAI assembly site.

### Affected CPNs:

[LIAL-07RPOQ740\\_Affected\\_CPN\\_08112022.pdf](#)

[LIAL-07RPOQ740\\_Affected\\_CPN\\_08112022.csv](#)

### Notification Text:

**PCN Status:**Initial Notification

**PCN Type:**Manufacturing Change

**Microchip Parts Affected:**Please open one of the files found in the Affected CPNs section.

Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

**Description of Change:**Qualification of a new lead frame with more Ag area on DAP surface prep for selected KSZ8081 and KSZ8091 device families available in 32L VQFN (5x5x0.9mm) package assembled at MTAI assembly site.

### Pre and Post Change Summary:

	Pre Change	Post Change
<b>Assembly Site</b>	Microchip Technology Thailand (HQ)/ (MTAI)	Microchip Technology Thailand (HQ)/ MTAI
<b>Wire material</b>	Au/2N	Au/2N
<b>Die attach material</b>	3280	3280
<b>Molding compound material</b>	G700LTD	G700LTD
<b>Lead frame material</b>	A194	A194
<b>Lead frame DAP surface prep</b>	Ag selective plating	Ag selective plating  (Add more Ag area)
	See Pre and Post Change Summary for comparison.	

**Impacts to Data Sheet:**None

**Change Impact:**None

**Reason for Change:**To improve productivity by qualifying new lead frame with more Ag area on DAP surface prep.

**Change Implementation Status:**In Progress

**Estimated Qualification Completion Date:**September 2022

Note: Please be advised the qualification completion times may be extended because of unforeseen business conditions however implementation will not occur until after qualification has completed and a final PCN has been issued. The final PCN will include the qualification report and estimated first ship date. Also note that after the estimated first ship date guided in the final PCN customers may receive pre and post change parts.

**Time Table Summary:**

	August 2022					September 2022			
Workweek	3 2	33	3 4	3 5	3 6	37	38	3 9	4 0

Initial PCN Issue Date		X							
Qual Report Availability							X		
Final PCN Issue Date							X		

**Method to Identify Change:**Traceability code

**Qualification Plan:**Please open the attachments included with this PCN labeled as PCN\_#\_Qual\_Plan.

**Revision History:**August 11, 2022: Issued initial notification.

The change described in this PCN does not alter Microchip’s current regulatory compliance regarding the material content of the applicable products.

**Attachments:**

- [PCN\\_LIAL-07RPOQ740\\_Pre and Post Change Summary.pdf](#)
- [PCN\\_LIAL-07RPOQ740\\_Qual Plan.pdf](#)

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

**Terms and Conditions:**

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If you wish to [change your PCN profile, including opt out](#), please go to the [PCN home page](#) select login and sign into your myMicrochip account. Select a profile option from the left navigation bar and make the applicable selections.

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Affected Catalog Part Numbers (CPN)

KSZ8091RNBCA  
KSZ8081MNXCA  
KSZ8091MNXCA  
KSZ8081MNXIA  
KSZ8081RNBCA-TR  
KSZ8091RNBCA-TR  
KSZ8081MNXCA-TR  
KSZ8091MNXCA-TR  
KSZ8081RNBIA-TR  
KSZ8091RNBIA-TR  
KSZ8081MNXIA-TR  
KSZ8091MNXIA-TR